ELECTRONIC & PHOTONIC PACKAGING DIVISION

DATE: January 9, 2025

TO: Electronic and Photonic Packaging Division Community

FROM: EPPD Executive Committee (ExComm)

SUBJECT: EPPD Collaborating with MIPE and ISPS

The Executive Committee of the Electronic and Photonic Packaging Division (EPPD) recently met with leaders from the Japan Society of Mechanical Engineers' (JSME) Information, Intelligence and Precision Equipment (IIP) Division regarding a collaboration between our two organizations beginning at the ASME InterPACK 2025 conference.

These discussions were a result of the recent sunsetting of the Information Storage and Processing Systems (ISPS) Division of ASME along with the ISPS Conference that they conduct. In the past, the ISPS Division also co-sponsored the Micromechatronics for Information and Precision Equipment (MIPE) Conference, conducted by the Japan Society of Mechanical Engineering. The sunsetting of ISPS Division is part of an initiative by ASME's TEC Sector Council to streamline and consolidate conferences and some divisions. The effort aims to improve the operations of the TEC Sector to better position TEC and ASME in the post-COVID environment. The consolidation will streamline operations, making ASME more agile and responsive to the needs of our members and the industry. By unifying resources, ASME can foster greater collaboration, innovation, and efficiency. This will enable ASME to provide even better support, resources, and opportunities for professional development to the entire membership.

When the TEC Council sunset ISPS, they asked the EPPD Executive Committee (ExCom) to incorporate ISPS members as well as conference content into EPPD and InterPACK. These efforts are already underway.

A recent meeting between EPPD and JSME IIP discussed possible collaboration at InterPACK 2025 by incorporating content for the MIPE Conference, which occurs once every three years. This conference alternates between Japan and the U.S. and has been co-sponsored by the former ASME ISPS Division. It was due to take place in the US in 2025 and with the sunsetting of ISPS, is looking for a collaboration to provide MIPE content in 2025. Additionally, JSME IIP would like EPPD to co-sponsor the MIPE conference in Japan in 2028.

The EPPD ExCom and InterPACK leadership team have approved incorporating the following broad tracks into InterPACK 2025 in order to include content from MIPE and expand the InterPACK conference scope and content:

- Micro/Nano Mechatronics, Microelectromechanical Systems and their Applications to Internet of Things
- Advanced Simulation in Science and Engineering
- Mechatronics, Tribology, and Control of Information Storage Systems and Robotics.

The EPPD ExCom would like to make the community aware about this collaboration and gather any questions or feedback you might have. Please send any questions or feedback to Barbara Zlatnik, Sr. Manager, TEC Operations at zlatnikb@asme.org.

We are excited to expand the content offered at InterPACK with the topics provided by the MIPE organizers and look forward to an even broader participation at InterPACK with the inclusion of MIPE and ISPS volunteers, authors and attendees.

Thank you.

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